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(21) International Application Number: PCT/US99/18433 (22) International Filing Date: 13 August 1999 (13.08.99) (30) Priority Data: 09/136,213 18 August 1998 (18.08.98) US (71) Applicant: INTEL CORPORATION [US/US]; 2200 Mission College Boulevard, P.O. Box 58119, Santa Clara, CA 95052-8119 (US). (72) Inventors: JAIN, Satchitanand; 558 Crimsonberry Way, San Jose, CA 95129 (US). RHEINHARDT, Dennis; 3440 Kenneth Drive, Palo Alto, CA 94303 (US). CHO, Sung-Soo; 1521 Jasper Drive, Sunnyvale, CA 94087 (US). (74) Agents: HELLER, Paul, H. et al.; Kenyon & Kenyon, Suite 600, 333 W. San Carlos Street, San Jose, CA 95110 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: METHOD AND APPARATUS TO CONTROL THE TEMPERATURE OF A COMPONENT		
<div style="text-align: center;"> <pre> graph TD 11[Control Device] --- Data[Data] --- 12[Component] 11 --- Temp[Temperature] 12 --- Temp </pre> </div>		
(57) Abstract <p>When a component, such as a memory device, exhibits an overtemperature condition (e.g., exceeds a first threshold value), the data transmission rate with respect to the component is reduced so as to lower its operating temperature. In one embodiment, this is achieved by changing the latency at which data packets are transmitted to and from the memory device in dependence on the temperature of the device. Controlling temperature in such a fashion allows for efficient use of the component over a large range of temperatures.</p>		